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Date: August 30, 2001

By *Shirley L. Quasi*

**IN THE UNITED STATES PATENT AND  
TRADEMARK OFFICE**

**PATENT**

Applicants: Yakov Epshteyn et al.

Docket No.: SFI 718D1

Serial No.: Not yet assigned

Parent Art Unit: 1763

Filing Date: August 30, 2001

Parent Examiner: S. MacArthur

**TITLE:** METHOD AND APPARATUS FOR  
REMOVING A MATERIAL LAYER  
FROM A SUBSTRATE

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
**Box PATENT APPLICATION**  
Washington, D.C. 20231

Dear Madam or Sir:

Prior to an examination of the above-identified divisional patent application, please enter the following Preliminary Amendment.

**In the Specification:**

On page 1, under the heading "**Cross-References to Related Applications**", please replace the paragraph directly below beginning on line 10 with the following paragraph:

This application is a divisional of U.S. Serial No. 09/736,472 filed on December 13, 2000, which is a continuation in part of U.S. Serial No. 09/415,898 filed on October 8, 1999, and of common assignee.

On page 10, please replace the first full paragraph beginning on line 9 with the following paragraph:

While the preferred embodiment of the invention has been illustrated and described, it will be appreciated that various changes can be made therein without departing from the spirit and scope of the invention. For example, the buff pad may include grooves or slurry holes. Further, the present invention may be applied to other, more primary, processes in which a rotating head is pressed to a circular wafer for the purpose of removing portions of the wafer surface. In this regard, the term "buff" pad and "buffing" as used herein are generically defined to mean a material removing article excluding a primary polish step.

### **In the Claims**

Please cancel claims 1-7, and renumber the remaining claims accordingly.

### **Remarks**

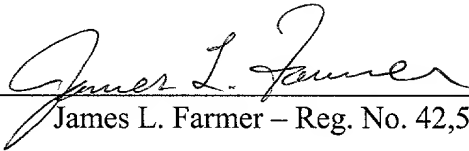
This divisional application is being filed to include the foregoing reference that the present application is a divisional of U.S. Serial No. 09/736,472 filed on December 13, 2000, which is a continuation in part of U.S. Serial No. 09/415,898 filed on October 8, 1999, and of common assignee. This preliminary amendment cancels claims 1-7 of application Serial No. 09/736,472 and renumbers the remaining claims as claims 1-18 of this application.

Regarding the correction made to the first full paragraph beginning at line 9 of page 10, the word "including" was mistakenly used instead of the intended correct word "excluding". By changing "including" to "excluding" the sentence is made consistent with the following paragraph which begins at line 16 of page 10.

Should the Examiner wish to discuss the above in greater detail, then the Examiner is invited to telephone the undersigned at the Examiner's convenience.

Respectfully submitted,

Date: August 30, 2001

By   
James L. Farmer – Reg. No. 42,525

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## MARKED-UP VERSION

### In the Specification

On page 1, under the heading “Cross-References to Related Applications”, the paragraph directly below beginning on line 10:

This application is a divisional of U.S. Serial No. 09/736,472 filed on December 13, 2000, which is a continuation in part of U.S. Serial No. 09/415,898 filed on October 8, 1999, and of common assignee.

On page 10, the first full paragraph beginning on line 9:

While the preferred embodiment of the invention has been illustrated and described, it will be appreciated that various changes can be made therein without departing from the spirit and scope of the invention. For example, the buff pad may include grooves or slurry holes. Further, the present invention may be applied to other, more primary, processes in which a rotating head is pressed to a circular wafer for the purpose of removing portions of the wafer surface. In this regard, the term “buff” pad and “buffing” as used herein are generically defined to mean a material removing article [including] excluding a primary polish step.